



CBR-SMD RF C0G, Ceramic, 6.7 pF, +/-0.25 pF, 50 VDC, C0G, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	12.03 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

Т	0.85mm +/-0.1mm	Dielectric Withstanding Voltage	125 \
В	0.5mm +/-0.2mm	Temperature Range	-55/
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.18
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% I
Packaging Quantity	4000	Insulation Resistance	10 G

Specifications	
Capacitance	6.7 pF
Tolerance	+/-0.25 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.187%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	534

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